

# つきまわり性に優れる6価クロムめっき用添加剤

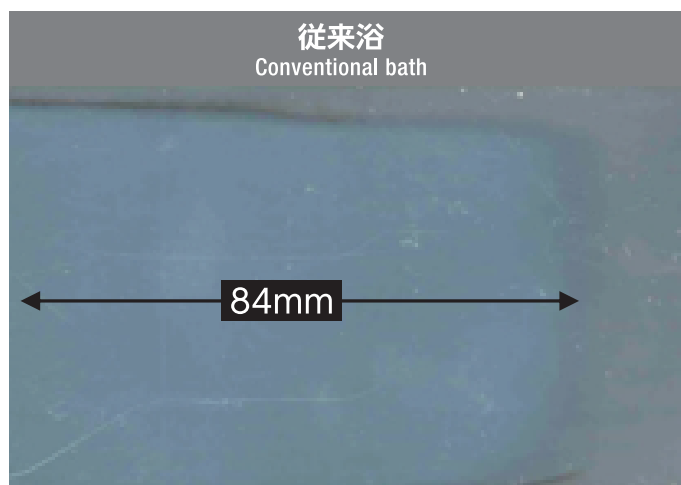
Additive for Hexavalent Chromium Plating with Great Covering Performance

# TOP DuNC CR

- つきまわり性に優れる  
Great covering power
- 浴中のフッ化物濃度が低く、陽極が溶解しにくい  
Fluoride concentration is low, prevent anode dissolution

## 優れたつきまわり性

Great covering power



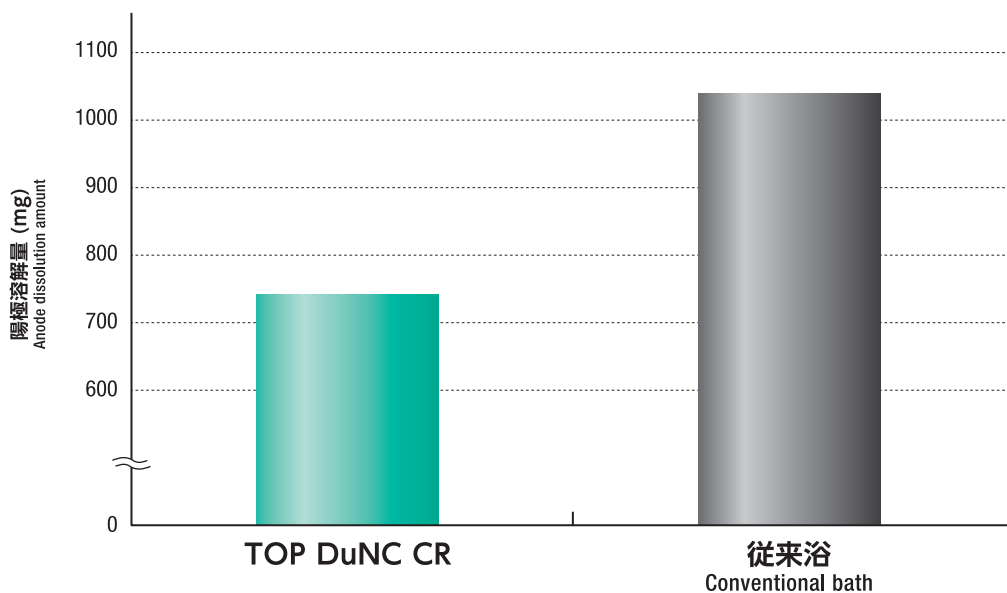
つきまわりの比較  
Comparison of covering performance

下地: 光沢ニッケルめっき, 添加剤にTOP DuNC BN使用  
Undercoat: Bright nickel plating film containing TOP DuNC BN as additive

ハルセル試験条件: 5A, 2分  
Hull-cell test condition min

## 陽極の溶解量が少ない

Prevent anode dissolution



※鉛-スズ5%の陽極に陽極電流密度10A/dm<sup>2</sup>で5分電解→5分停止のサイクルを24時間繰り返し、陽極の重量変化を測定(陽極面積0.2dm<sup>2</sup>)  
\*Prepare Pb-Sn5% anode (0.2dm<sup>2</sup>) and conduct plating for 5 min at 10A/dm<sup>2</sup> of anode current density, then stop plating and wait for 5 min.  
Repeat the procedure for 24 hours to evaluate anode dissolution amount.